

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: <b>W1903-01</b>	DATE: 13-Mar-2019	MEANS OF DISTINGUISHING CHANGED DEVICES:			
Product Affected: P9221-R7AHGI P9221-R7AHGI8		☐ Product Mark ☐ Back Mark ☐ Date Code ■ Other		Fab location is ne 2 digit sequential e code line of the top	
Date Effective: 13-Jun-2019					
Contact: IDT PCN DESK		Attachment:	Yes	☐ No	
E-mail: pcndesk@idt.com		Samples: Please cor sample red	ntact your local sales quest.	s representative for	
DESCRIPTION AND PURPOSE OF CHANGE:					
Die Technology Wafer Fabrication Process Assembly Process Equipment Material Testing Manufacturing Site Data Sheet Other	abrication Process ly Process This is to provide additional manufacturing capacity for these products. There is no change to the product design or process technology as the existing qualified Foundry, TSMC Fab 8.  There is also no change to the package, backend manufacturing process or the the data sheet.				
	Refer to page 2 for the qualification report.				
Based on wafer and component level qualification to date and characterization tests, there is no change to the performance or reliability of the product.  CUSTOMER ACKNOWLEDGMENT OF RECEIPT:  IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.					
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory					
on the earlier version has been depleted.					
Customer:		Approval for s	hipments prior t	o effective date.	
Name/Date:	E-	Mail Address:			
Title:	Phone# /Fax# :				
CUSTOMER COMMENTS:					
IDT ACKNOWLEDGMENT OF RECEIPT:					
RECD. BY:		DATE:			